

COMMON DIMENSIONS				No. of
Symbol	MIN.	NOM.	MAX.	Ter
A	—	—	1.20	
A <sub>1</sub>	0.05	—	0.15	
A <sub>2</sub>	0.95	1.00	1.05	
b	0.17	0.22	0.27	13
b <sub>1</sub>	0.17	0.20	0.23	
c	0.10	—	0.21	
c <sub>1</sub>	0.10	—	0.16	
D	—	20.00 BSC	—	4
D <sub>1</sub>	—	18.40 BSC	—	5
E	—	8.00 BSC	—	5
e	—	0.50 BSC	—	5
L	0.50	0.60	0.70	6
N	—	28	—	
O	0°	3°	5°	

NOTES:

1. DIE THICKNESS ALLOWABLE IS 0.292±0.013mm (.0115±.0005 INCHES)
2. DIMENSIONING & TOLERANCES PER ASME Y14.5M. - 1994.
3. DATUM PLANE [H] LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXIST PLASTIC BODY AT BOTTOM OF PARTING LINE.
4. DATUM [A-B] AND [D] TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXIST PLASTIC BODY AT DATUM PLANE [H]
5. "D1" & "E" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm ON E AND 0.25 ON D1 PER SIDE.
6. DIMENSION IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
7. TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
8. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN 0.076mm AT SEATING PLANE.
9. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPAGE BETWEEN PROTRUSIONS AND AN ADJACENT LEAD TO BE 0.07mm SEE DETAIL "B" AND SECTION "C-C".
10. "X" DENOTES MOLD CAVITY IDENTIFICATION.
11. "COO" DENOTES COUNTRY OF ORIGIN.
12. TO BE DETERMINED AT SEATING PLANE [C].
13. SECTION "C-C" TO BE DETERMINED AT 0.10 TO BE 0.25 MM FORM THE LEAD TIP.
14. CONTROLLING DIMENSION: MILLIMETERS.
15. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-142 VARIATION BD.
16. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLATE TO THE LOWEST POINT OF THE PACKAGE BODY.

TITLE	
PACKAGE OUTLINE, 28 LEAD, MATRIX, TYPE I, 8 X 20 TSOP	
REV	REV
B	03
DATE	32934
SCALE	SHEET 2 of 2